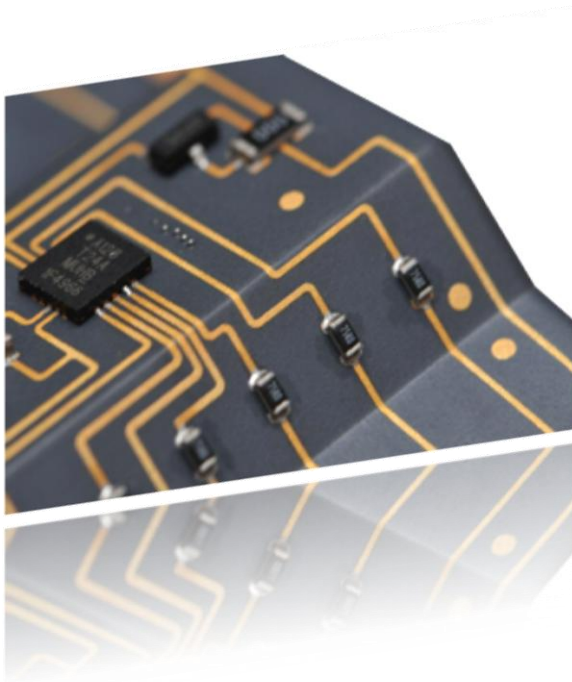


When plastics meet electronics for smart plastic products



info@s-2p.com www.s-2p.com
+33 4 74 81 81 10

September 2015



An innovative technological context...

○ Smart Plastic Products

- A smart plastic product is a complex 3D plastic part that **interacts with its environment** through the integration of « smart » functions
- These smart functions can be made by active material, or by the integration of **electronic components**.

○ 3D-MID (Molded Interconnect Devices) are made by selective plating technologies that enable to build in one sub-assembly :

- The mechanical function
- The electronic function
- And the packaging function





...answering market needs



3D-MID benefits

- Functions integration / Miniaturization
- Design freedom
- Assembly simplification
- Weight reduction
- Process flexibility
- Technical and esthetic functions mixing
- **Global production cost optimization**



3D-MID functions

- Antennas
- Sensors
- LED Lighting
- Tracks, 3D PCB
- Battery holder
- Anti intrusion structures
- EM Shielding
- Connectors
- Local heating
- Decoration

Source: BMW,, Citec/Uni Bielefeld



WHO ARE WE ?

From prototyping to series, on the full value chain.



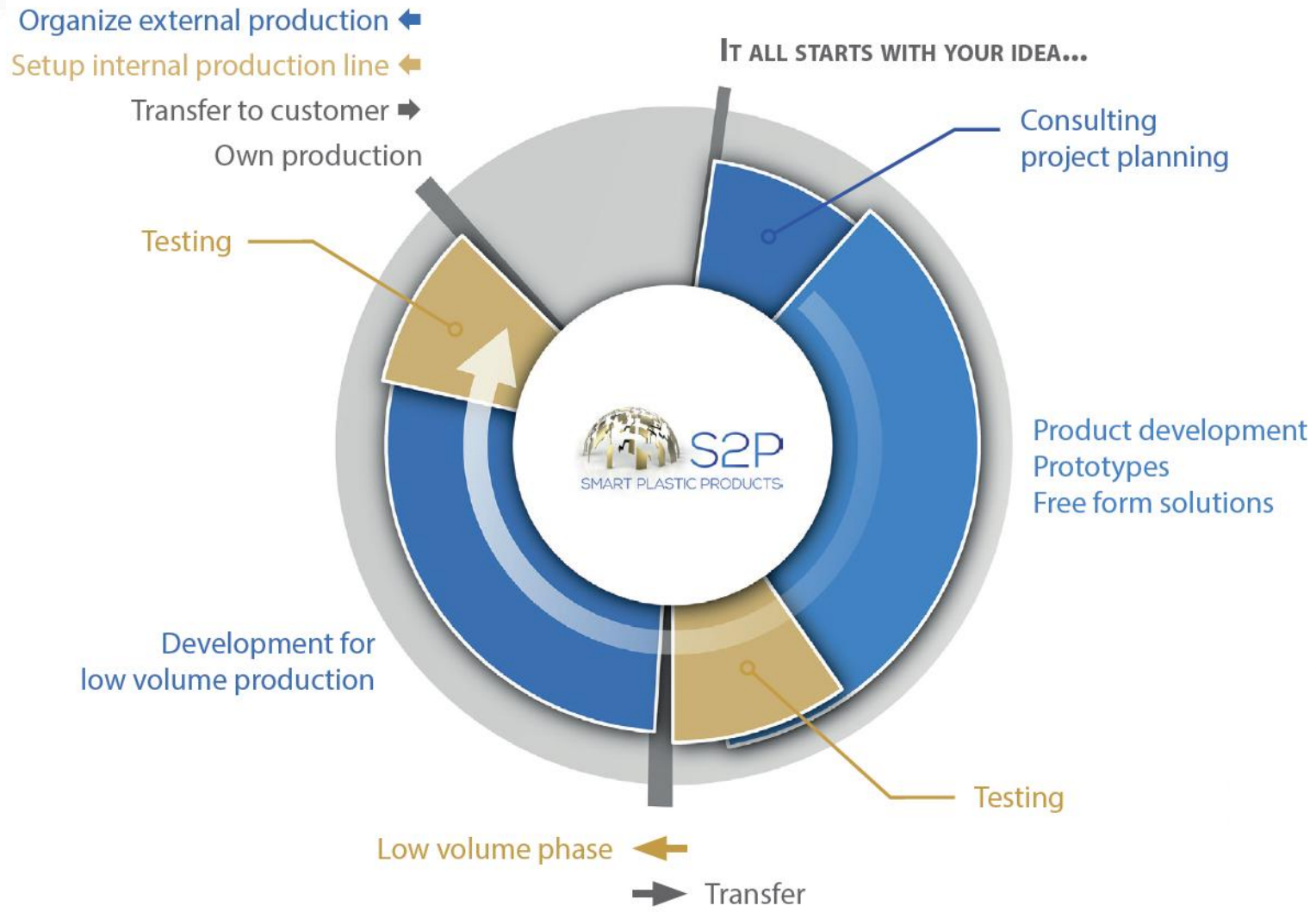
S2P in words



- **SME company located in Oyonnax-France**, in the heart of the Plastic-Valley
- Spin off of **PEP**, the **French technical center for plastics and composites**, after 10 years of R&D on 3D MID technologies.
- Specialized in services for **designing, prototyping and manufacturing** of smart plastic products.
- **A multidisciplinary team** of technicians, engineers and doctors in **mechanics/ plastics, chemicals and electronics**.
- **Our goal** is to give to the industry the possibility to:
 - Develop and manufacture these new products without having to invest heavily in the short term on the means and skills
 - Transfer technologies to partners wishing to invest
 - Benefit from a technological incubator through the development of emerging technologies in 3D-MID to manufacture the next generation of Smart Plastic Products

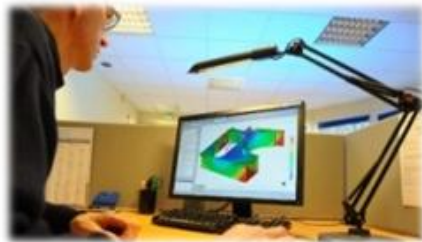


S2P in words : our services





S2P in words : our means



1. Product design



2. Plastic/composite substrate manufacturing



3. Selective activation



4. Plating



5. Component assembly



6. Quality control

**Design to cost !
Optimal co-design of
products integrating the
full process flow**



S2P KEY TECHNOLOGIES

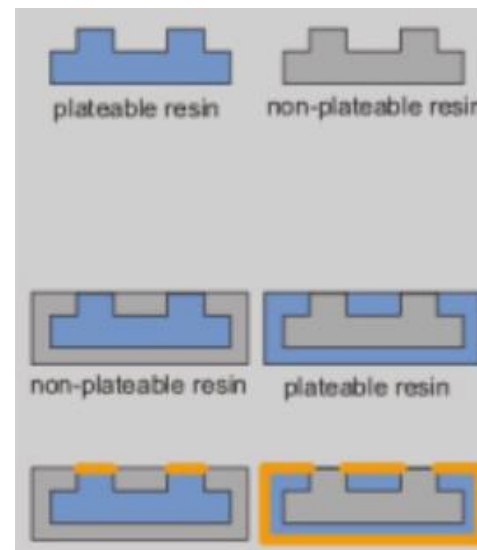
2-Shot Molding, Laser Direct Structuring, Plasmacoat 3D



2-Shot Molding

- 2-Shot molding (3D masking)
 - Chemical surface activation
 - Electroless Cu plating
 - Surface finishing: Ni+Au / Ag
-
- Benefits :
 - Short process
 - Cost effective on high volumes

 - Drawbacks :
 - 2-Shot tool investment
 - Low flexibility
 - Mainly signal applications
 - Few material available



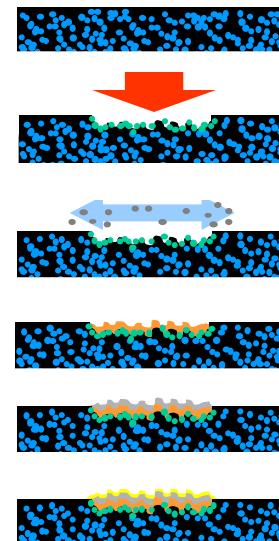
Source: Bosch



Laser Direct Structuring – LDS®



- Single material injection molding
- 3D laser activation
- Electroless Cu plating
- Surface finishing : Ni+Au / Ag / Sn

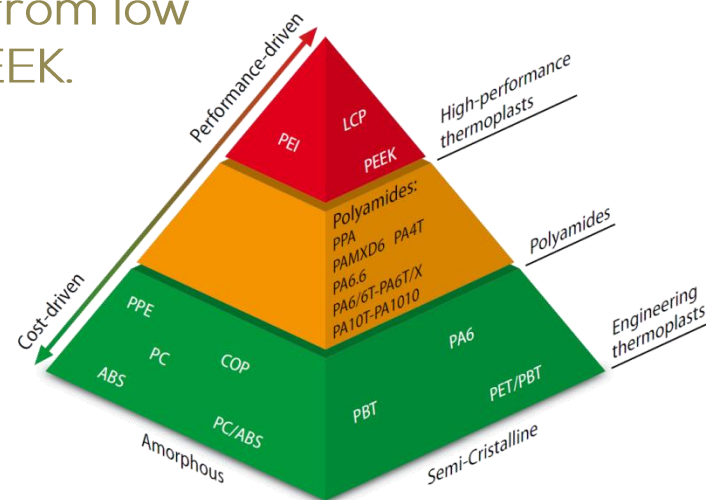


Benefits :

- High flexibility
- From prototyping to very high volumes
- More and more materials available: from low cost ABS up to high performance PEEK.

Drawbacks :

- Mainly signal applications





LDS® Smart Composites !



- LDS process can be used on thermosets !

- Raschig GmbH: Epoxidur EP 3915, epoxy resin processable by Bulk Moulding Compound (BMC) injection.
- Other thermosets are under development: phenolic, polyester





Laser Direct Structuring – LDS®



● Possibility to increase the copper layer by **galvanic plating** (electroplating)

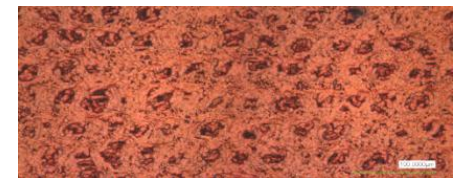
- up to $1\mu\text{m}/\text{min}$: 65% time reduction compared to electroless-only
- Decrease of roughness down to $R_a=0,2\mu\text{m}$

Example on PC-ABS Xantar LDS 3710

- . E-less Cu : $R_z=11,4\mu\text{m}$; $R_a=1,2\mu\text{m}$
- . Galv. Cu : $R_z=1,4\mu\text{m}$; $R_a=0,2\mu\text{m}$



Cu $35\mu\text{m}$ / NiP $4\mu\text{m}$ / Au $0,1\mu\text{m}$



Source: LPKF

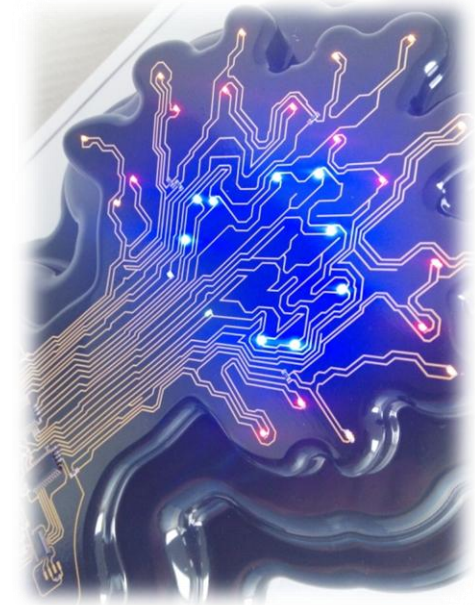


LDS® rapid prototyping



○ Several possibilities

- 3D machining of LDS polymer blocks
- Use of an innovative LDS lacker (activable and platable) on parts made by machining, conventional injection moulding, or even rapid prototyping technologies (SLM, FDM, ...)
- Conventional injection moulding in rapid prototyped thermoset moulds !



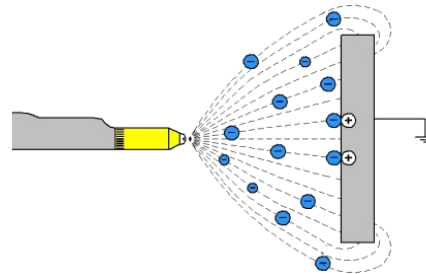
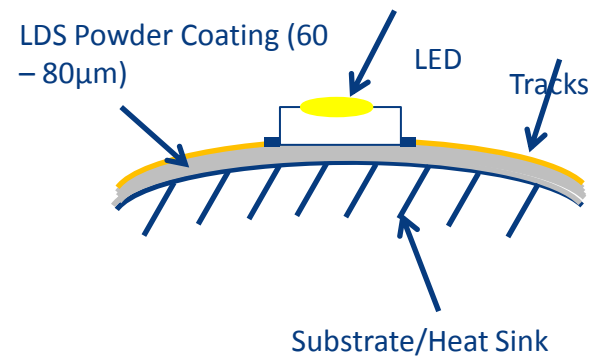


LDS® PowderCoating



Integration of electronics on 3D metal parts !

- We apply a **powder lacquer** (dry PU or PES based) by electrostatic spraying on conductive materials
- After curing, **standard LDS** steps are applied.
- The coating is appropriate for **reflow soldering** at 240/270°C
- Well suited for **thermal management** !

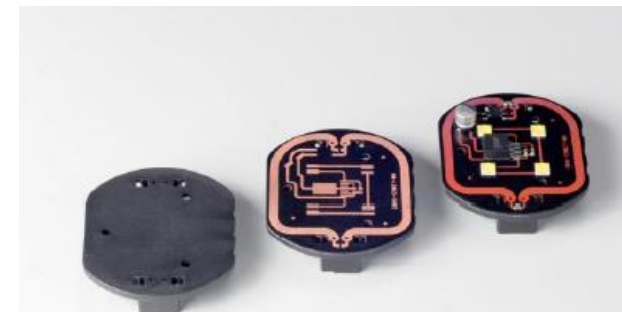




Plasmacoat 3D



- Polymer substrate or other
- 2D or 3D masking
- Plasma copper coating
- Benefits :
 - Dry metal deposition (integration in an existing production plant)
 - Important thickness possible for power applications
 - Possible on transparent materials
- Drawbacks:
 - Low complexity parts
 - Material validation needed for plasma parameters optimization



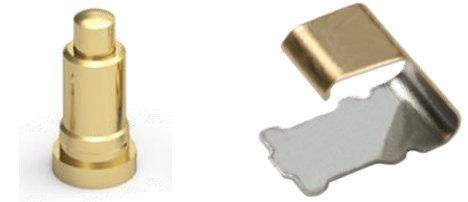
Source: Plasma Innovation, LPKF, RF Plast, Polyone



Assembly of 3D-MID

○ Mechanical interconnections

- Pogo pins, spring contacts, zebra contacts, press-fit, etc.
- Use of the plastic part elasticity to make pressure contacts (on PCB, batteries, ...)



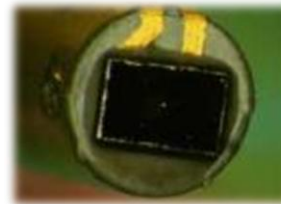
○ Compatible with SMD assembly !

- Dispensing of up to lead-free solder pastes
- Pick & place of electronic components
- Standard 2D or specific 3D available
- Reflow soldering, laser soldering



○ Chip assembly

- wire-bonding
- flip-chip



○ Possibility to use 3D-MID as macro-components on PCB





APPLICATIONS AND MARKETS

Telecommunication, automotive, industry, medical...

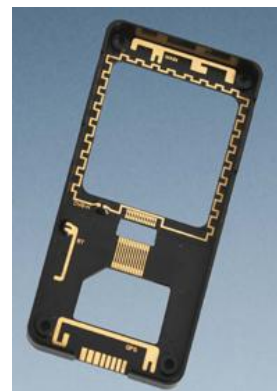


Telecommunication & connected objects

- First world market of 3D-MID
- **From DC to more than 10 Ghz**, perfect for antennas !
NFC, UHF, GSM, 3G, 4G, Wifi, Bluetooth, LORA/Sigfox, etc
- Towards the integration of antennas directly on covers



iid G9

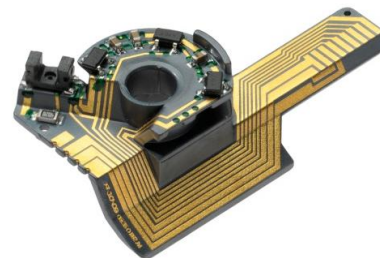


Source: Molex, TE, Samsung, Nexus, Sony

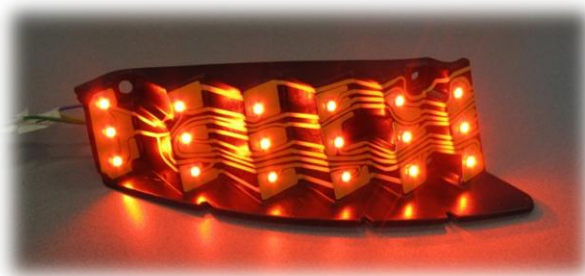


Automotive / transportation

- Interconnections modules
- Sensors
- Switches
- Antennas
- LED Lighting



Module for adaptive cruise control in ARS 300
(Harting Mitronics for Continental, LCP LDS)



Rear Lighting(CRP Italie, PA LDS)



Steering wheel switches (BMW
Z4 Roadster, PBT LDS)

ESP pressure sensor (BOSCH, LCP bi-matière)



„Shark“ antenna(BMW, LCP LDS)

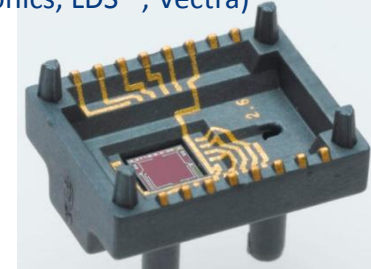
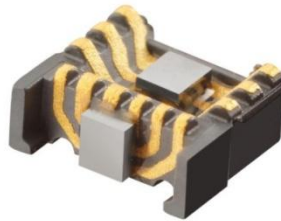




Industry

- Smart packaging
- Function integration
- LED
- Antennas (RFID)

Sensor , designed for SMT mounting on PCB
(HARTING Mitronics, LDS ®, Vectra)



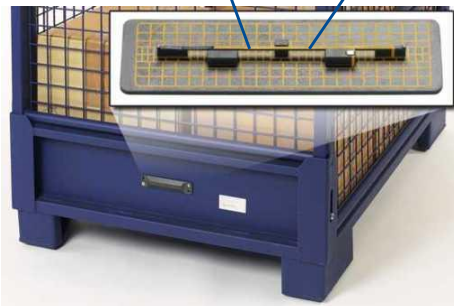
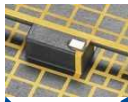
Lighting System for Security
Camera v300 ws (HARTING
Mitronics for SICK, LCP LDS



OLED lighting by OSRAM



RFID transponder
(HARTING Mitronics, LDS
®, Vectra)



Bionic ant by Festo (LDS Prototaint)





Medical

- 3D electronic circuitry
- Function integration
- Ergonomics

Microphone module for
hearing aid (HARTING
Mitronics for Siemens, LDS[®]
Vectra)



Switch element
(HARTING Mitronics
for KaVo Dental, LDS[®],
Vectra)



3D-circuit-board for dental
hand-piece (KaVo Dental
Excellence, LDS[®], Ultramid)



LED Carrier (2E mechatronic
& Laser Micronics for KaVo
Dental, LDS[®], Vectra)





CONTACT

info@s-2p.com

+33 4 74 81 81 10 - www.s-2p.com

2 rue Curie – 01100 Bellignat – FRANCE

S2P is supported by



bpifrance

Rhône-Alpes Région

l'ain
Conseil général

**HAUT
BUGEY**
COMMUNAUTÉ DE COMMUNES